

Evaluation of Heat Transfer in High-Temperature Refractory Foam Heat Exchangers using Computational Fluid Dynamics

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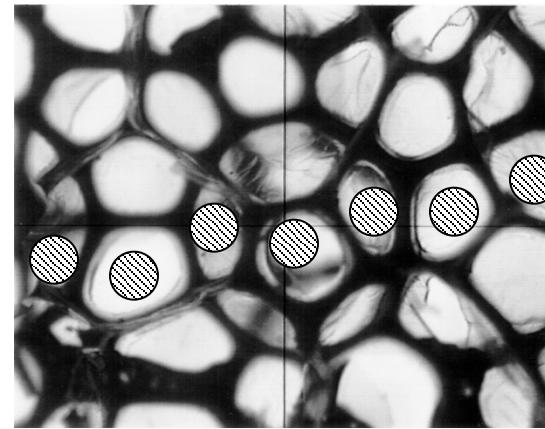
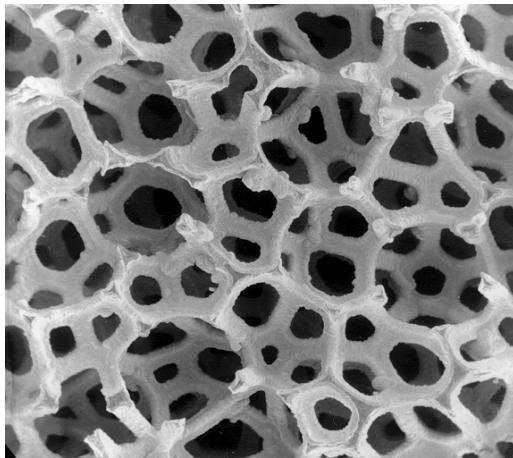


Outline

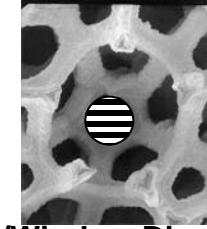
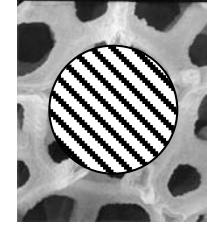
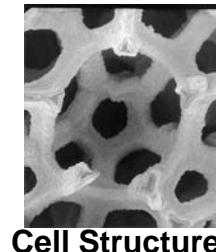
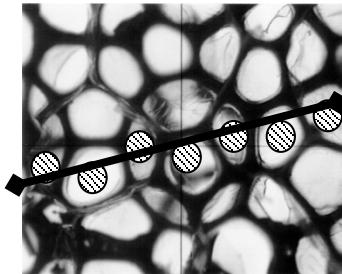
- Porous media - Foam geometry
- Computerized micro-tomography
- Model generation
- Meshing
- Conjugate heat transfer with CFD
- Heat exchanger applications
- Thermal stress analysis



Foam Nomenclature



PPI = Pores Per Inch



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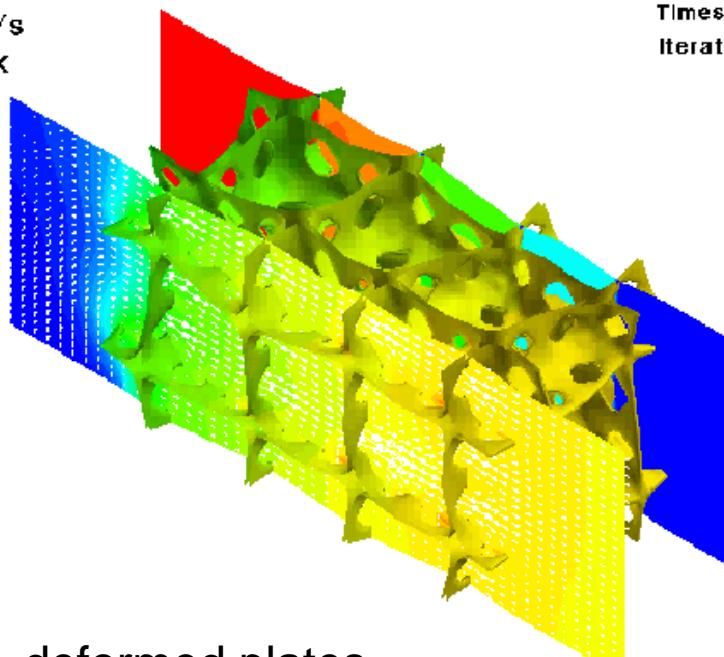
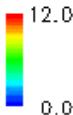
Previous modeling relied on periodic structures.

Foam Model - 77% Porosity

$V_{in} = 0.1 \text{ m/s}$

$K = 25 \text{ W/m-K}$

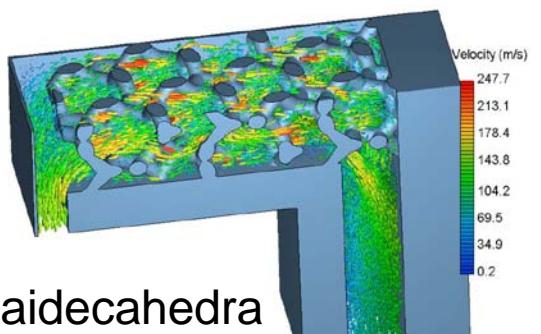
Temp Change, K



Time = 0.1–0.5 sec

Timestep = $1e-5$

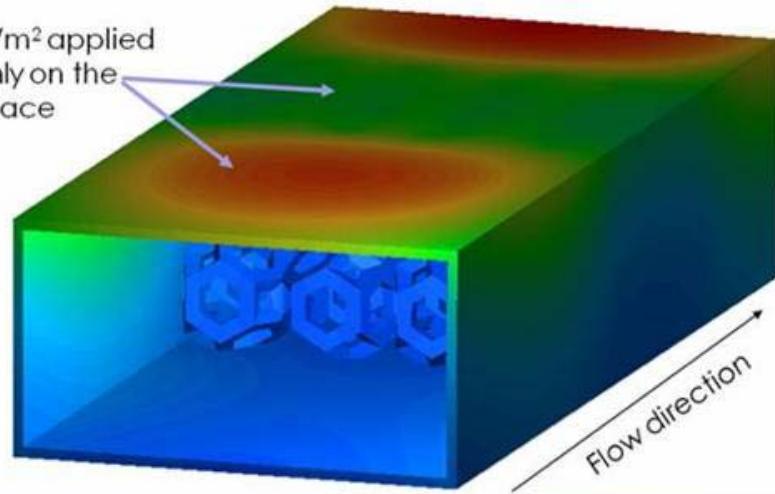
Iteration = 1,000



tetrahexahedra

873.00 927.08 981.16 1035.25 1097.05 1151.14 1205.22 1259.30

10 MW/m² applied uniformly on the top surface



All other faces have adiabatic conditions

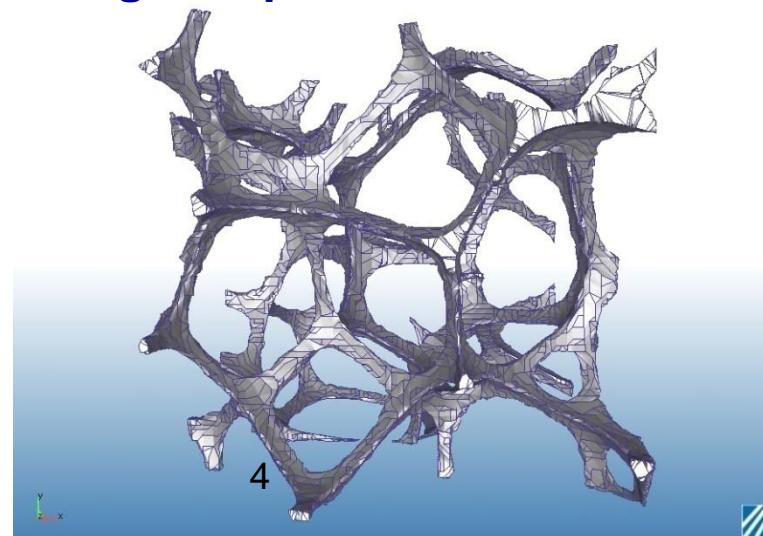
Failed to capture the randomness in cell size, window orientation, non-uniform ligaments and other unique characteristics of commercial foams.



We perform CFD modeling of foam porous media heat transfer on the microscale.

- Computerized X-ray microtomography was completed at Sandia on Ultramet supplied foam samples. The smaller files were translated from stereolithography format to ACIS solid modeling format.
- The solid models of the detailed foam microstructure were meshed and analyzed by commercial computational fluid dynamics (CFD) codes (CFDesign and CCM+) to determine the effective permeability and ligamental heat conduction.
- Foam models derived from computerized x-ray tomography were closed with facesheets of SiC on one side and steel on the other inside CCM+.
- The CCM+ tet mesh was exported to Abaqus for stress analysis.
- Deflections, inelastic strains and stresses were computed in the ligaments and permeation barrier facesheets using Abaqus.

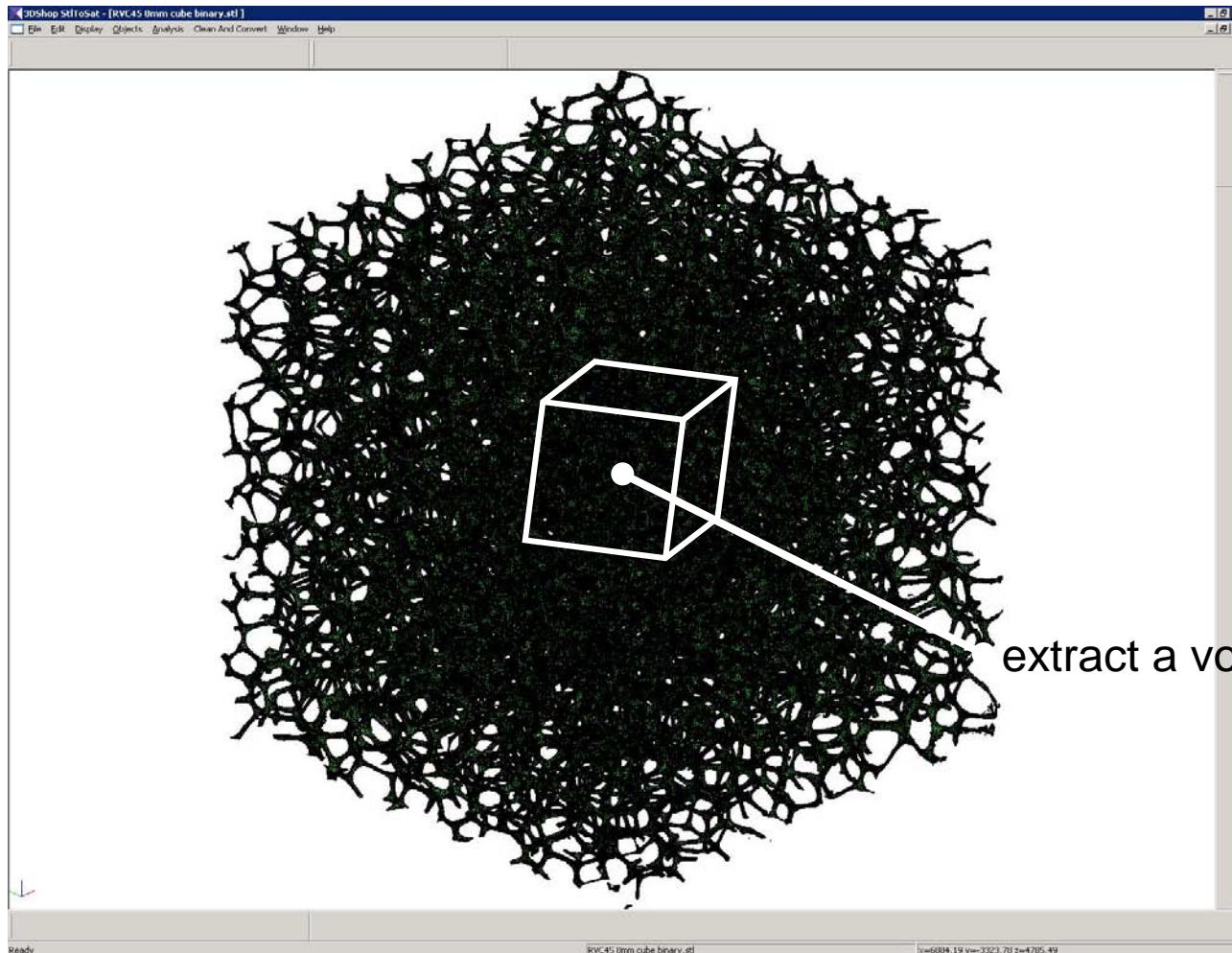
X-ray microtomography file of carbon foam after translation to ACIS solid modeling format.





Processing geometry and meshing are greatest challenge.

8 mm x 8 mm x 8 mm 45 ppi RVC skeleton



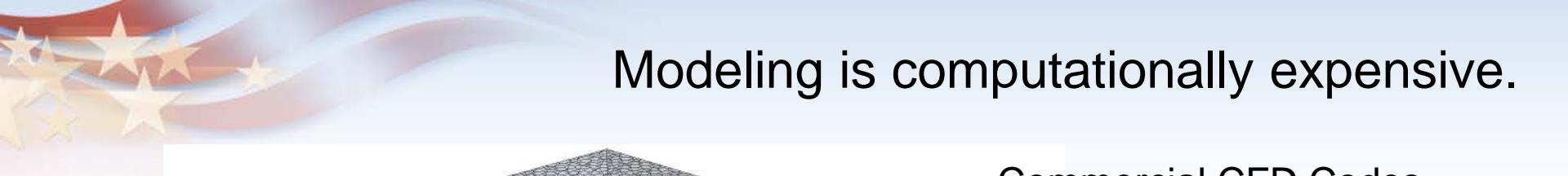
Tomography

- VGStudio MAX by Volume Graphics

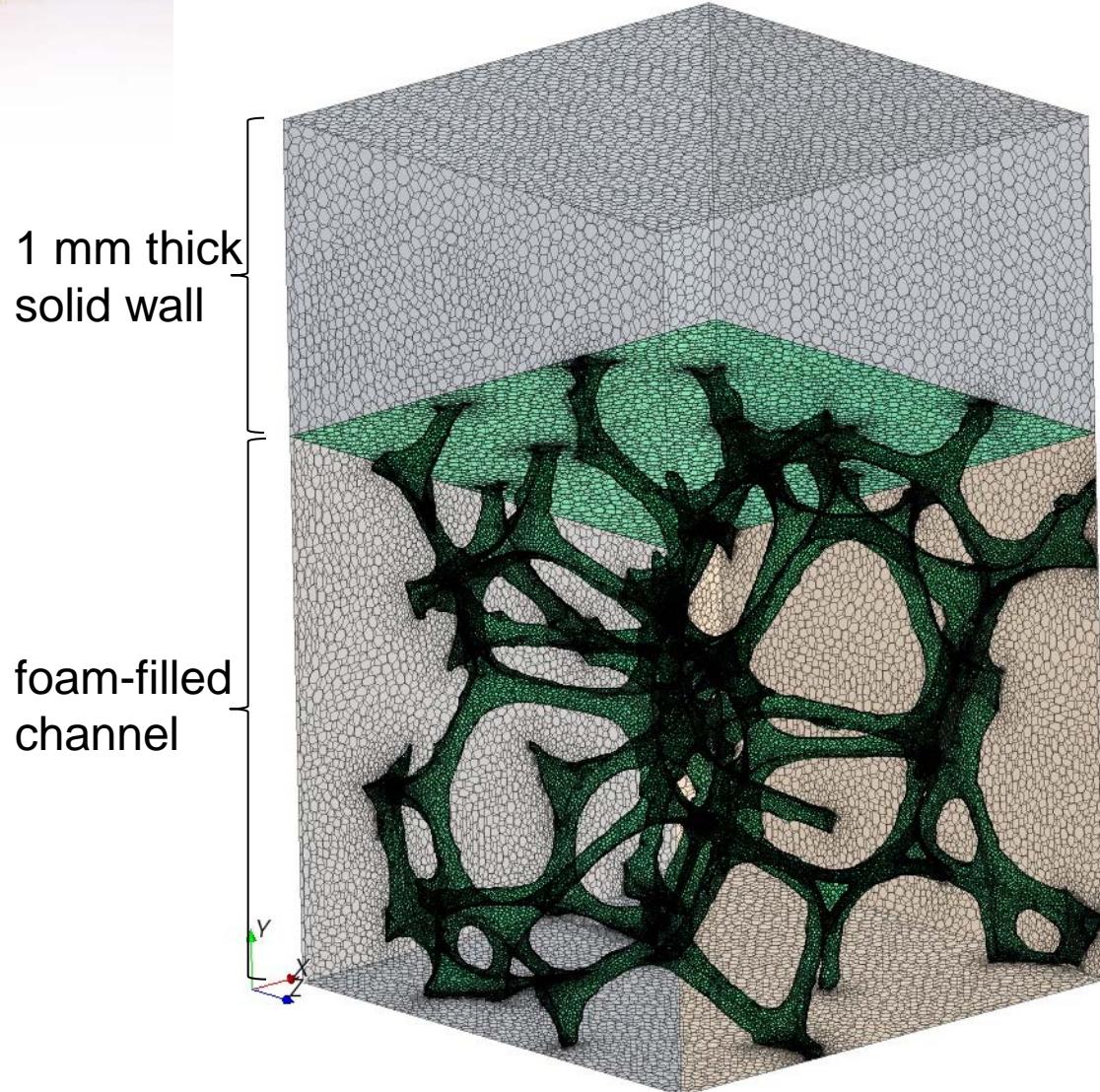
File translation

- 3dShop by C4W
- Rhino 3d
- Cubit
- Star CCM+

extract a volume



Modeling is computationally expensive.



Commercial CFD Codes

- Star-CCM+ v5.04
- Cfdesign v10

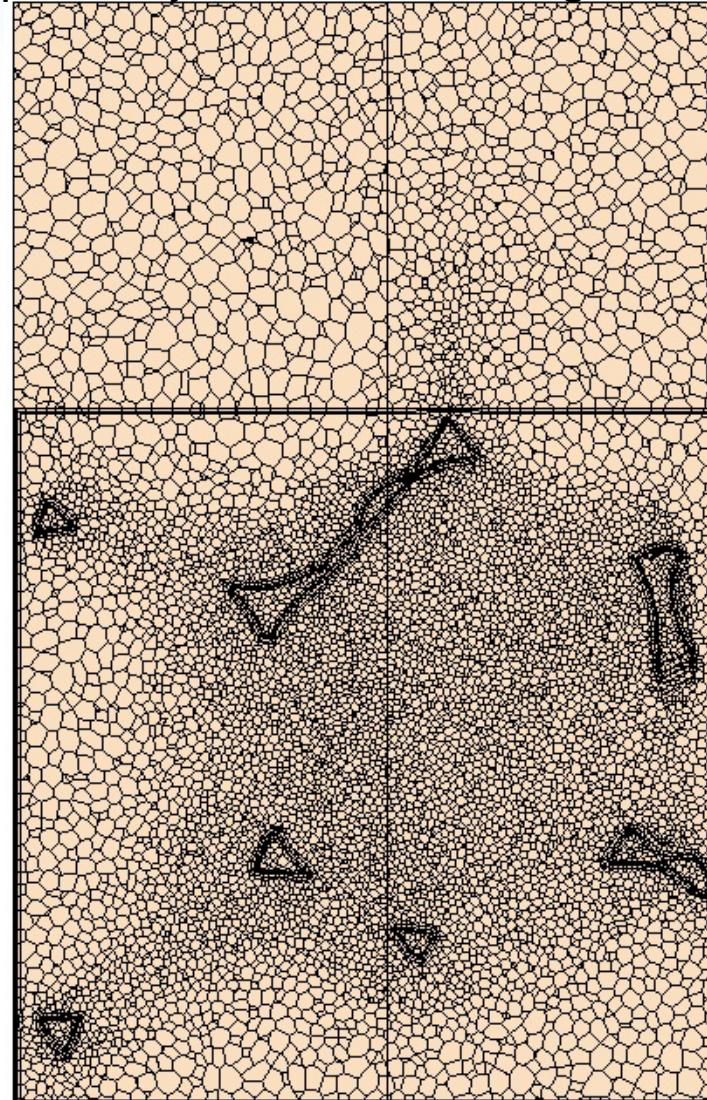
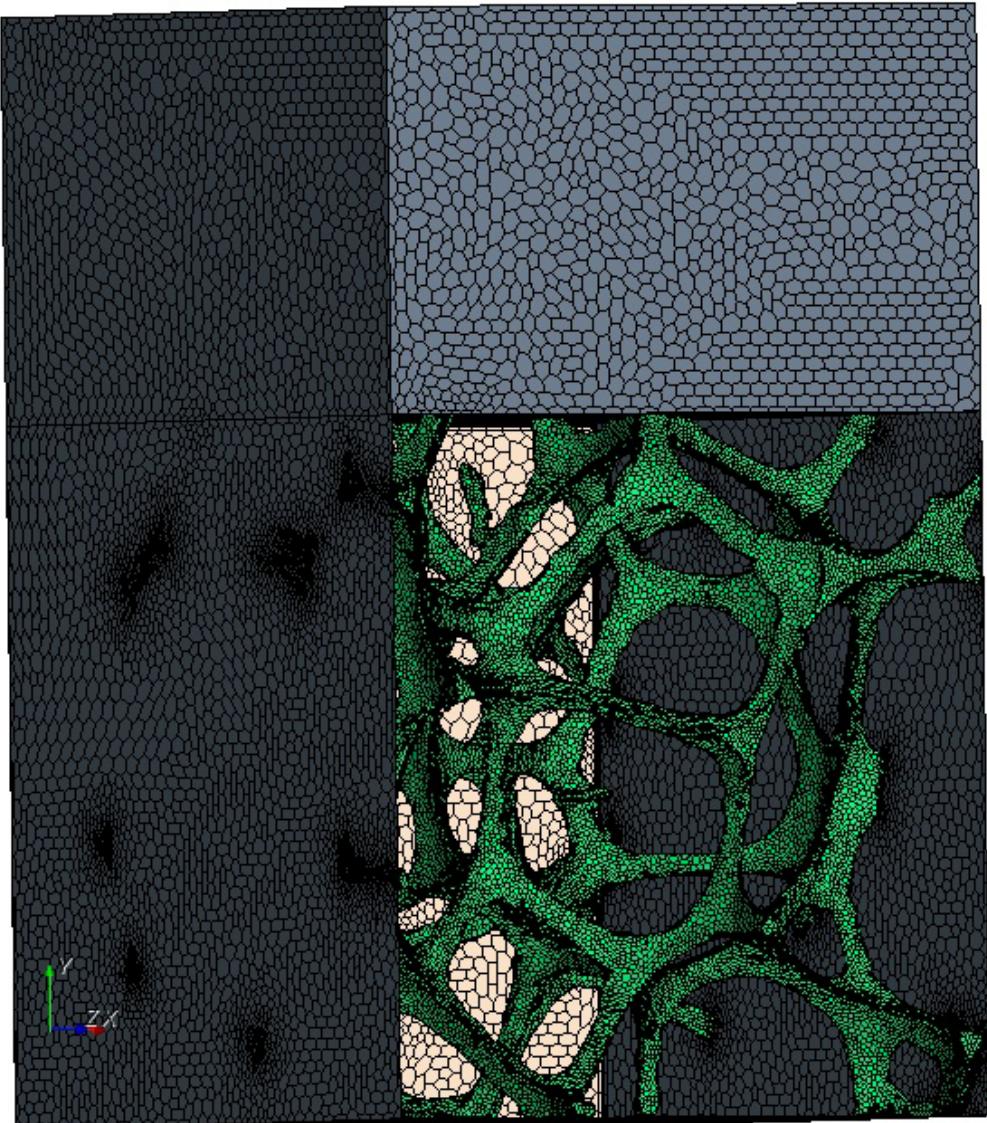
One-million element polyhedral mesh with three prism layers at all solid/gas interfaces.

1.7 mm x 1.7 mm x 2.7 mm high. Arbitrarily chosen volume extracted from 8x8x8 mm³ volume shown earlier. Wall added in CCM+.



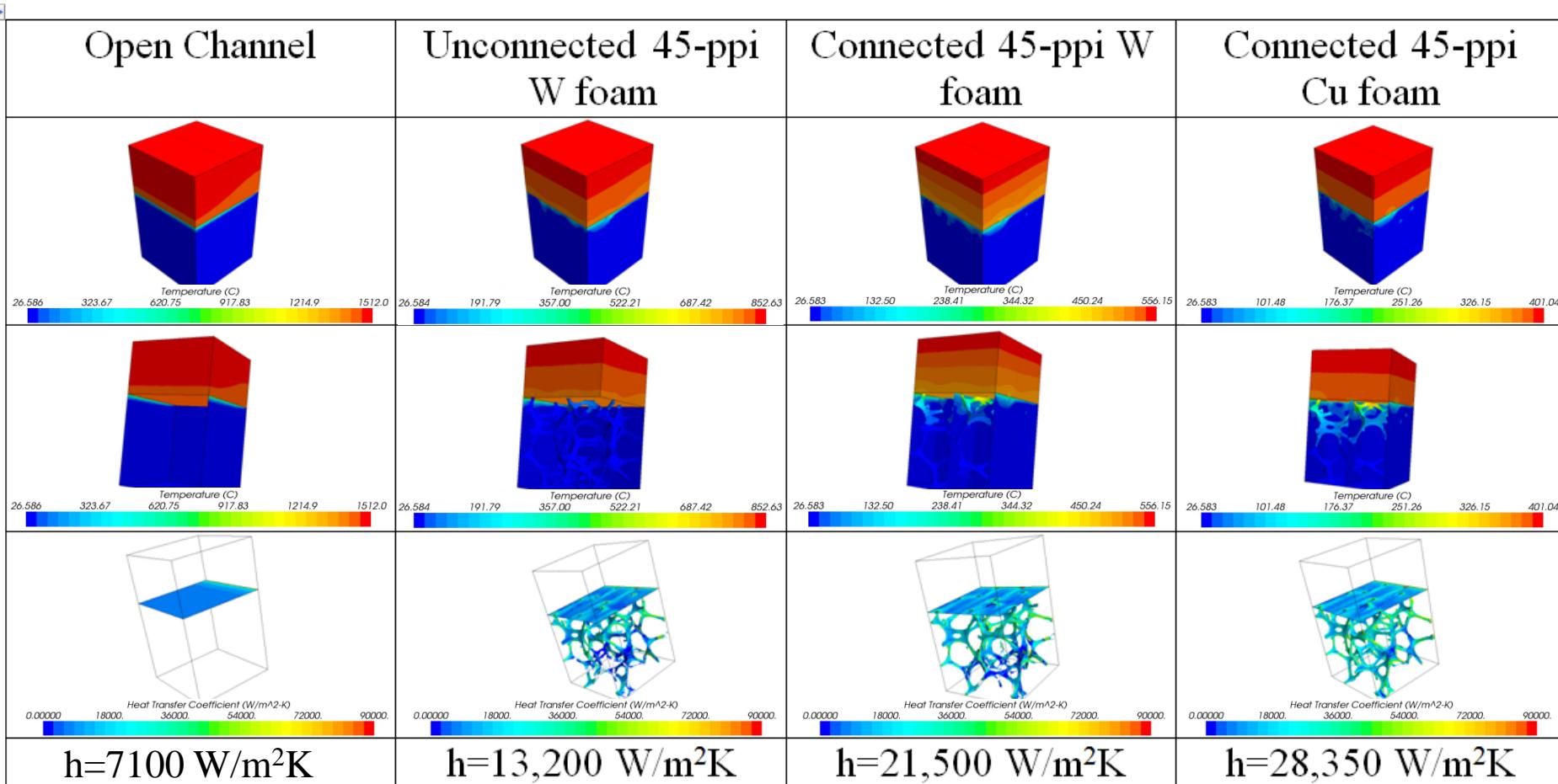
Imprint and merge 3 solids and a fluid

3 prism layers at walls and ligaments

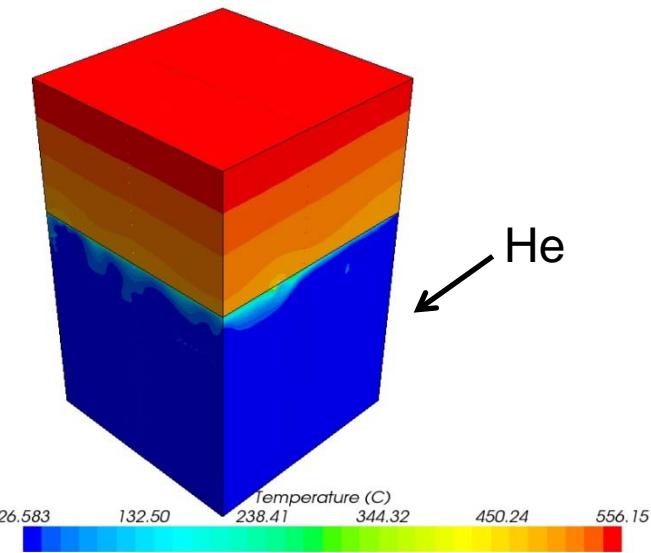
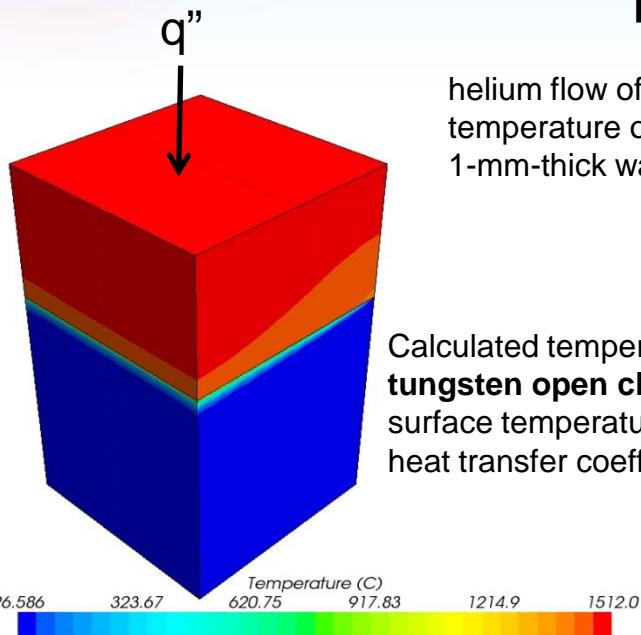


Porous media is effective in enhancing gas cooling.

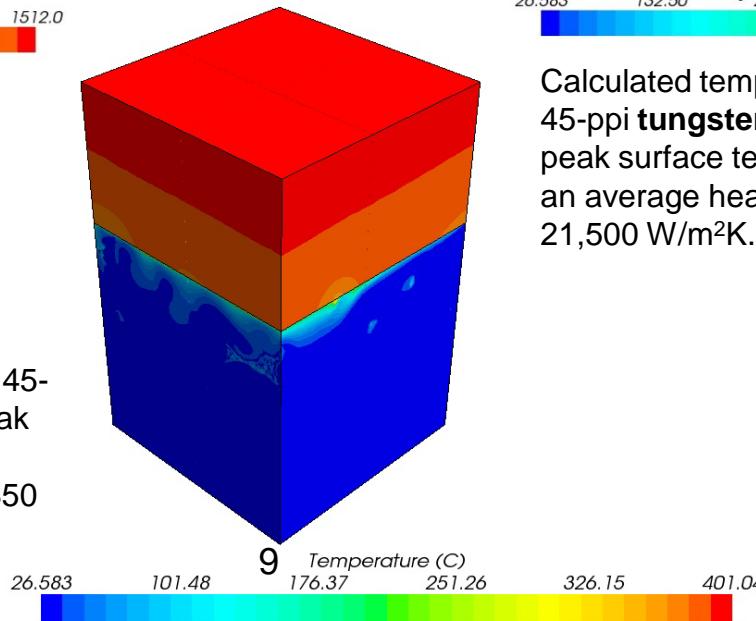
Table 1. Comparison of Foam Effectiveness to Open Channels



Conductivity of foam can affect performance.

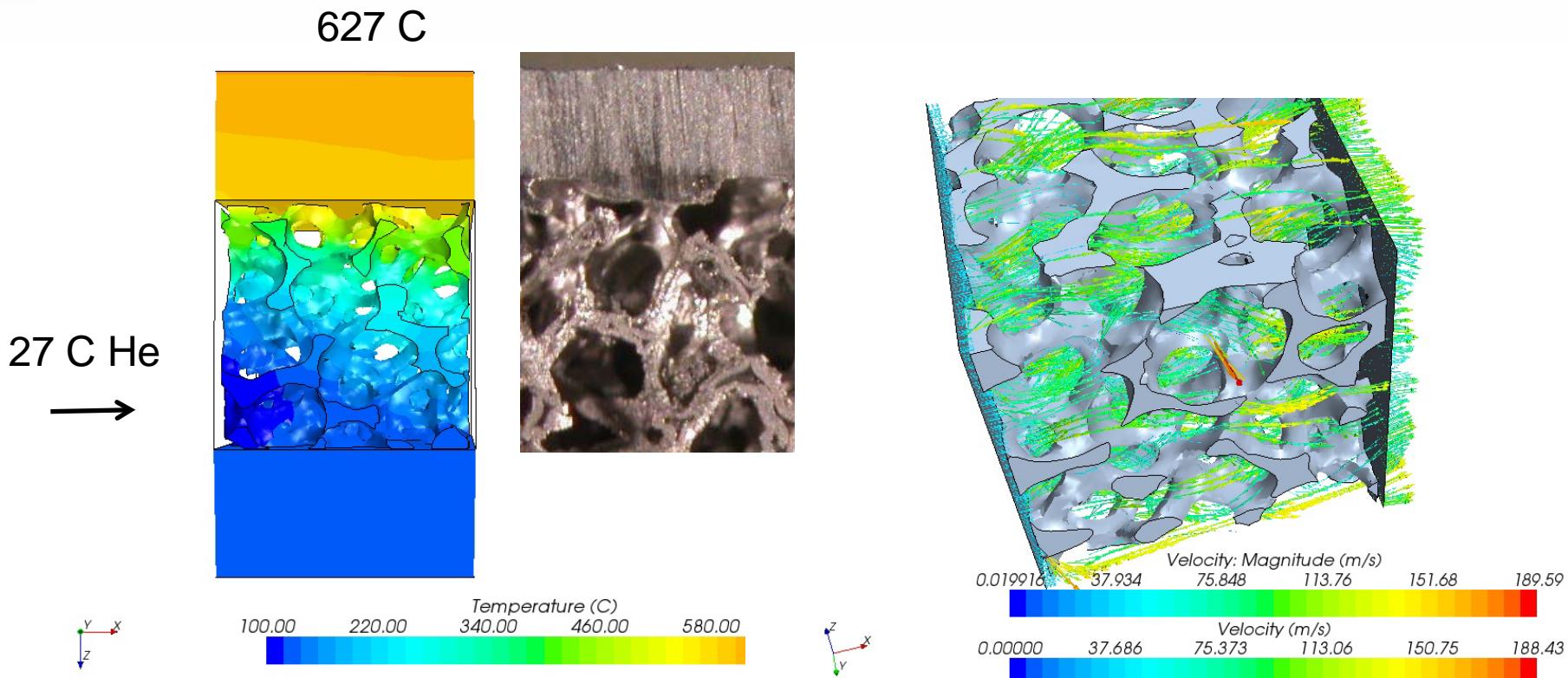


Calculated temperature distribution in a 45-ppi **copper foam channel** reveals a peak surface temperature of 401 °C with an average heat transfer coefficient of 28,350 W/m²K.



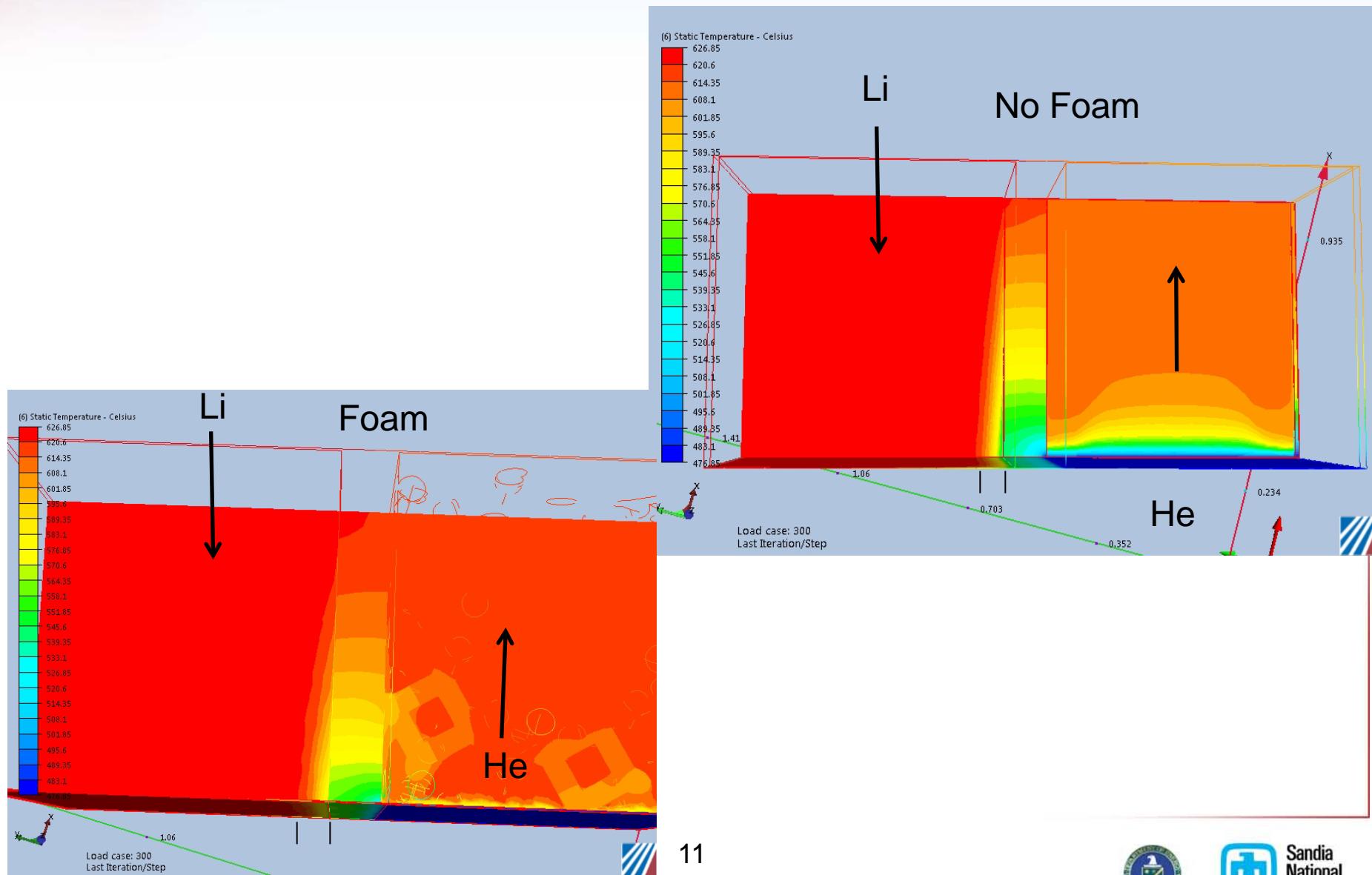


Analysis reveals turbulent mixing and fin effect created by foam.



Convection models for 2 mm x 2 mm 65 ppi, 10% dense moly foam attached to 1 mm thick moly walls. Temperature distribution is shown on left with velocity vectors and streamlines through the foam on the right.

Foams can enhance heat transfer in open channels of dual coolant schemes if the foam is bonded to the intervening wall.



Refractory heat exchangers are under fabrication.

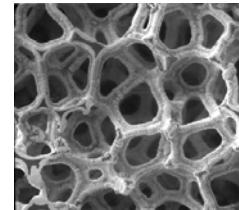
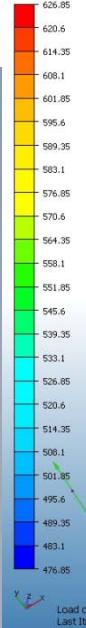
All Mo



High temperature He/He regenerator

High temperature Li/He heat exchanger

(6) Static Temperature - Celsius



$$\varepsilon_{hx} = (T_c, \text{He out} - T_c, \text{He in}) / (T_h, \text{Li in} - T_c, \text{He in})$$
$$\varepsilon_{hx} = h_L A_L / (m \cdot \dot{V}_L C_{p(L)}) / [1 + h_H A_H / (m \cdot \dot{V}_H C_{p(H)})]$$

HX effectiveness



Li/He design concept

- The classic counterflow flat plate heat exchanger can have high specific area, on the order of $3000 \text{ m}^2/\text{m}^3$. This design can be improved if refractory foam is added to the gas channels. Molybdenum foam on the order of 65 ppi and 20% dense can have a specific surface area as high as $7000 \text{ m}^2/\text{m}^3$ exposed to helium.
- The dendritic molybdenum coating can increase the lithium-exposed area by a factor of two to three depending on dendrite size (shape and height). This new configuration more than doubles the convective heat transfer area between lithium and helium.
- Since the dendrites and foam are integrally bonded to the wall, conduction through the thermal boundary layer is enhanced from the lithium into the bulk helium gas stream, improving the heat transfer by an additional 10%.
- The foam on the helium side promotes turbulence and mixing, resulting in a very low temperature difference between the inlet lithium and exit helium (several degrees). The dendrites aid wetting of the molybdenum wall by lithium, yet do not represent a restriction or increase the pressure drop by reducing the channel size to the point where surface tension and capillary forces dominate.

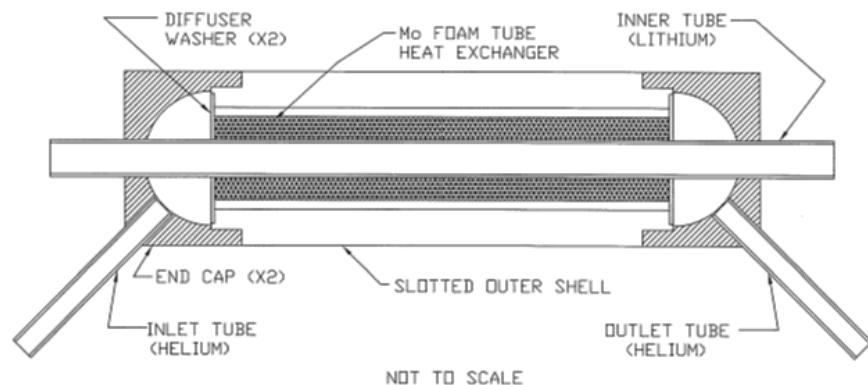
LiHe HX Prototype



Views showing Mo Inner Tube + Mo foam fully slid into the ID of Mo

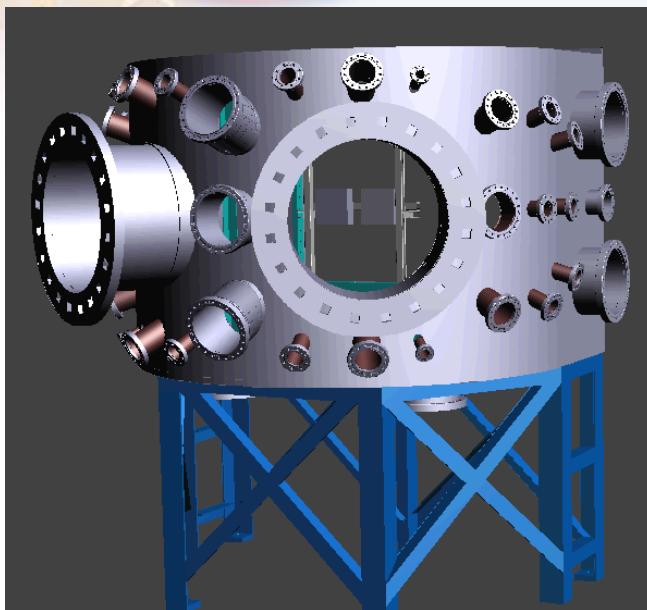


Mo foam heat exchanger slid over Mo inner Tube with dendritic internal coating

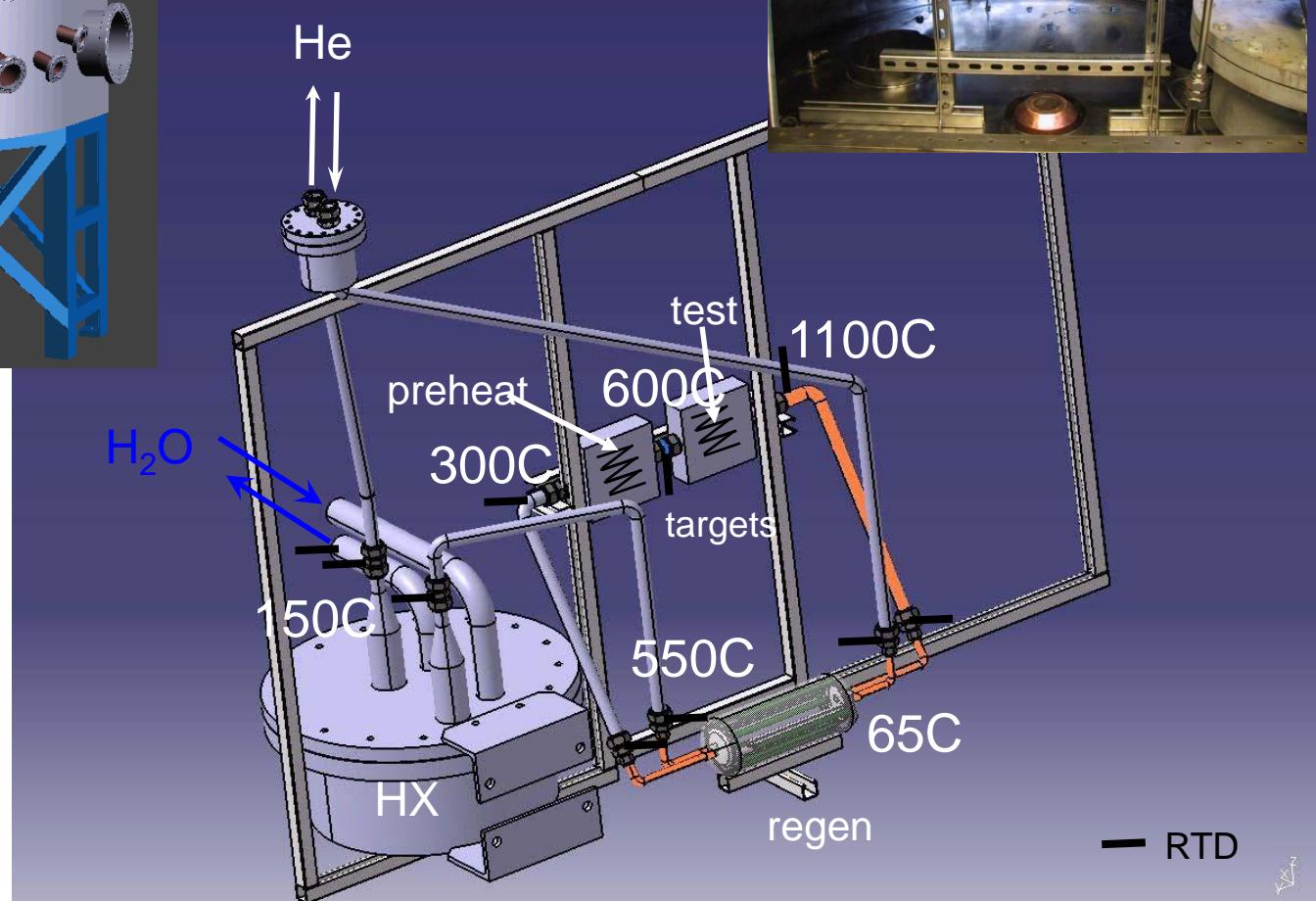


Fully-Assembled Prototype (before brazing)

HHF testing of helium-cooled panels underway at PMTF.

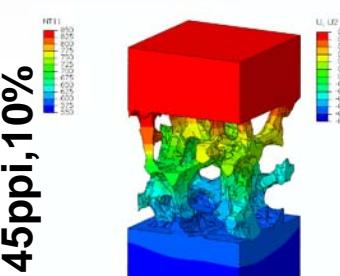


- Short hi-temp runs (Mo)
- In-vacuo
- Experimental
- Low cost
- Small impact on HeFL loop

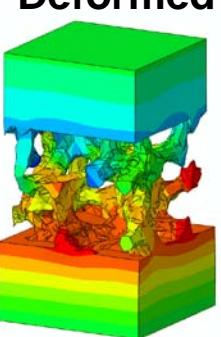


Modeling of SiC Foam

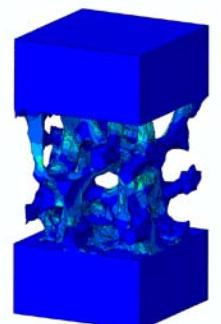
Temperature



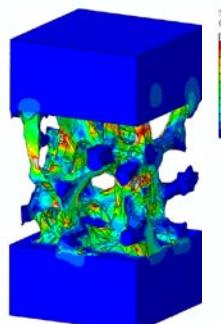
Vertical Deformed



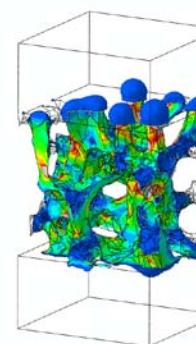
Mises All



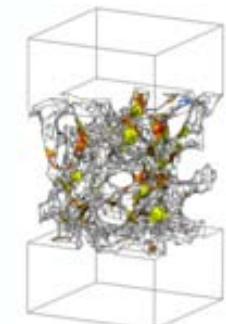
Maximum



Over 500



Over 3000

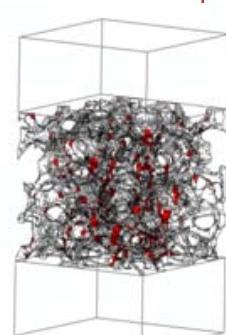
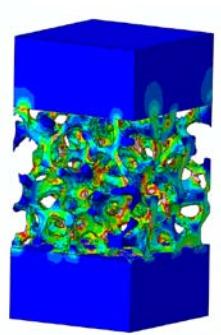
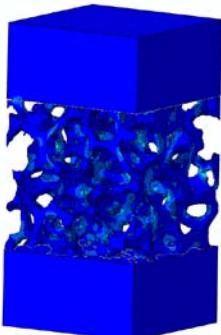
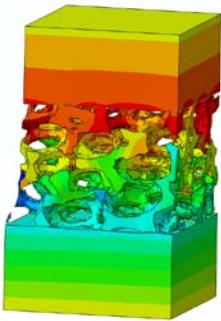
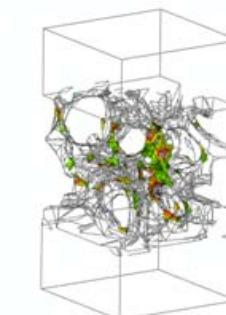
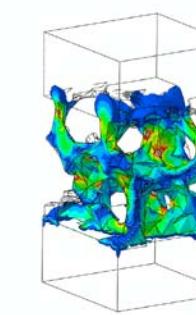
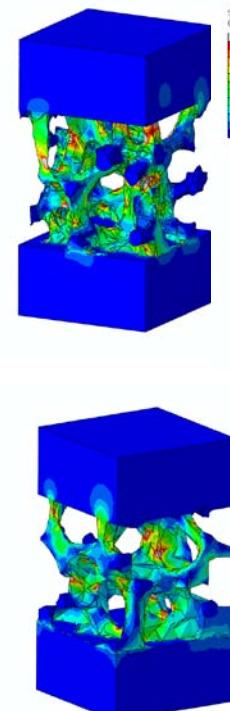
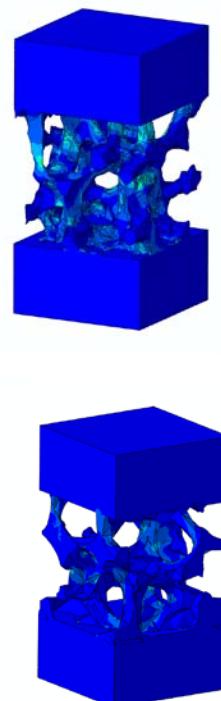
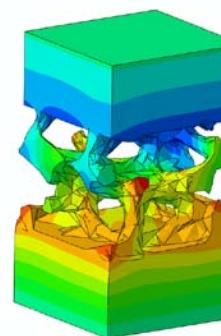


45ppi,10%

45ppi,15%

65ppi,10%

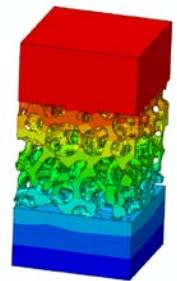
Vertical Deformed



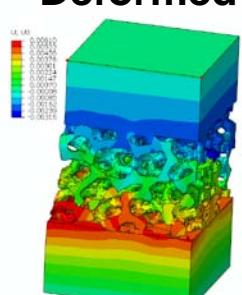
Modeling of SiC Foam

Temperature

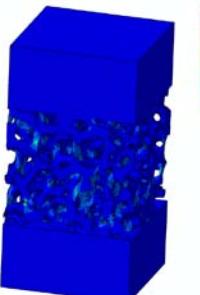
65ppi,25%



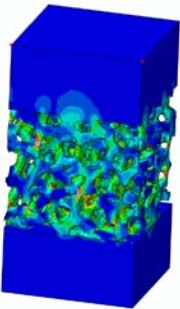
Vertical Deformed



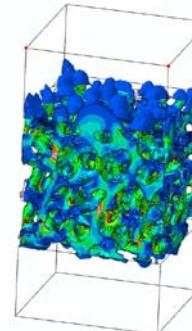
Mises All



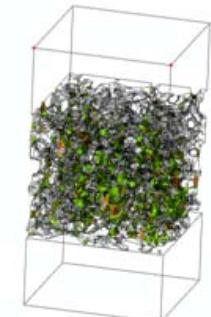
Maximum



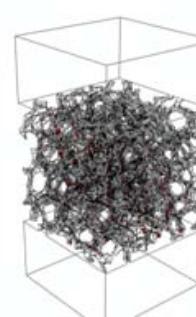
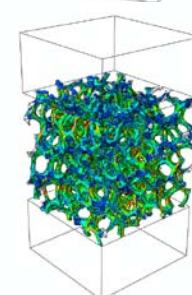
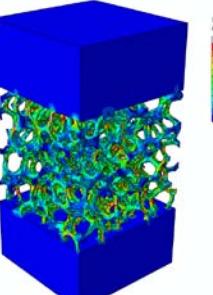
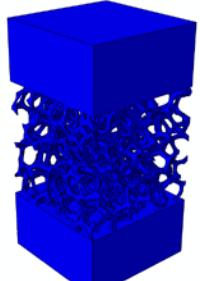
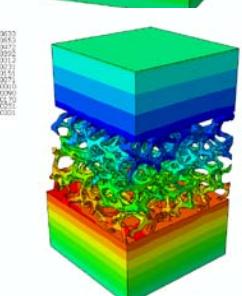
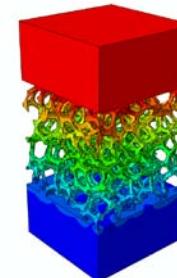
Over 500



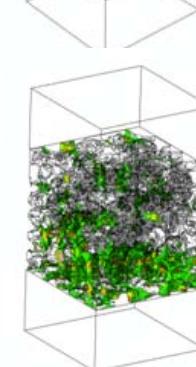
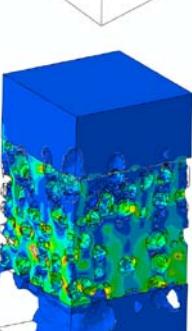
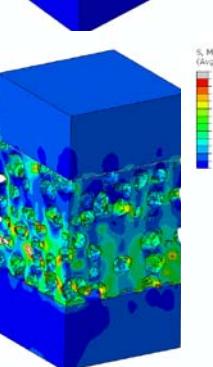
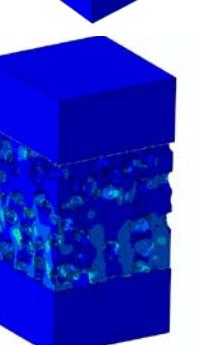
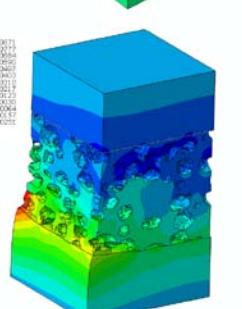
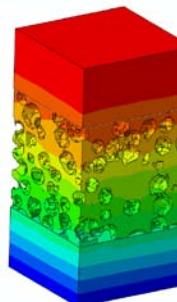
Over 3000



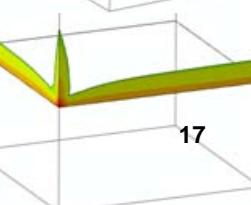
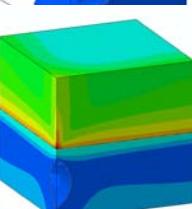
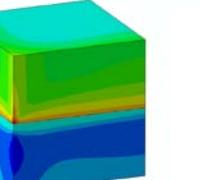
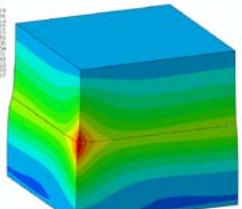
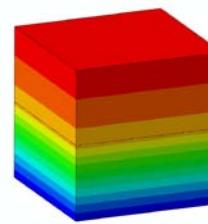
100ppi,10%



100ppi,20%



plates



Modeling of Nb Foam

Temperature

Vertical
Deformed

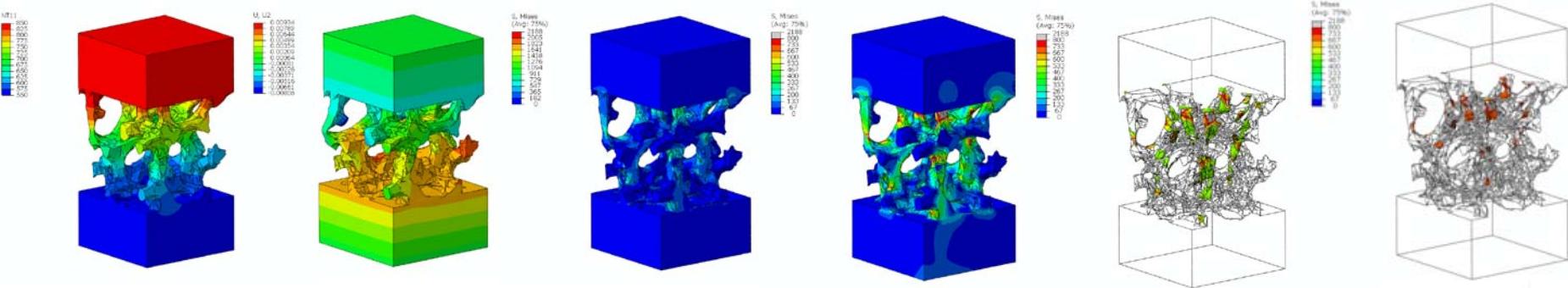
Mises All

Maximum

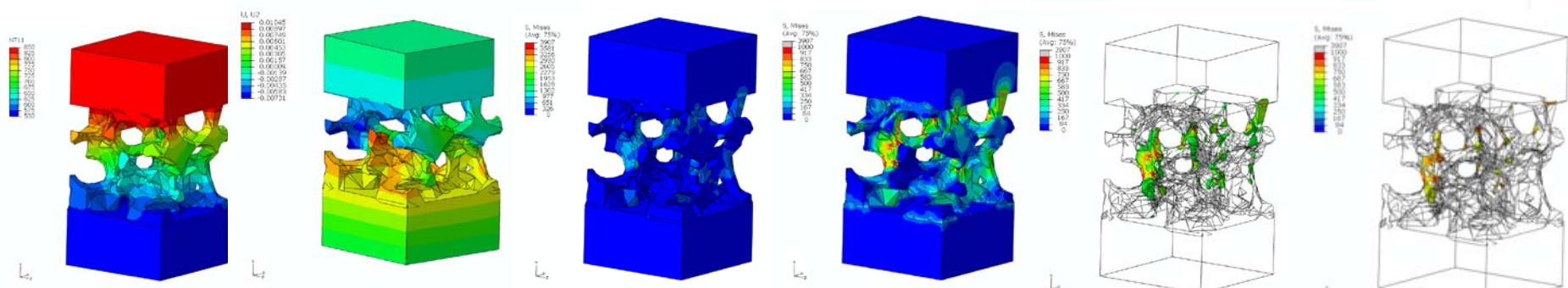
Over 500

Over 700

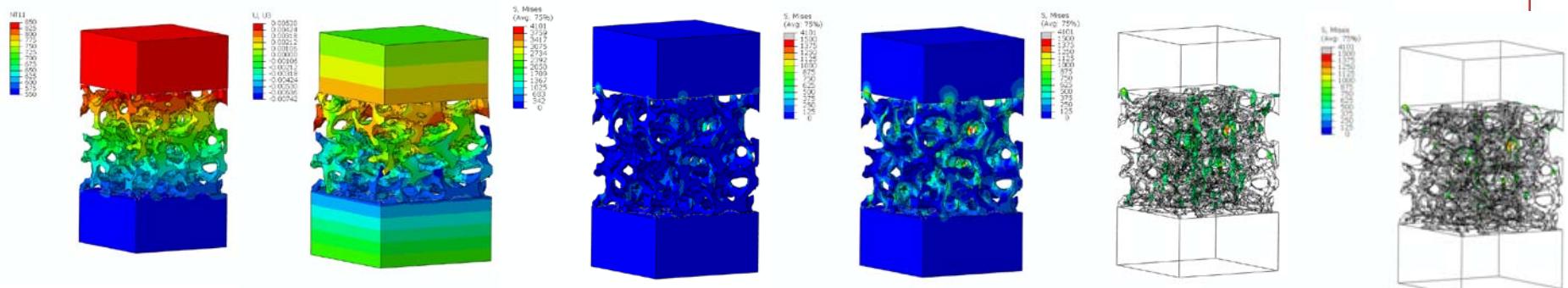
45ppi,10%



45ppi,15%

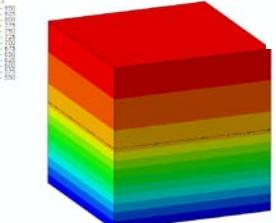
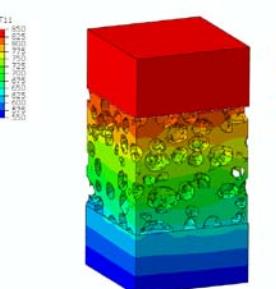
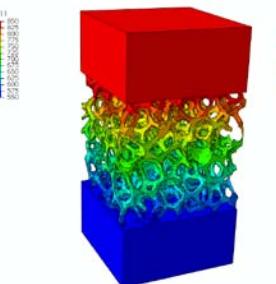
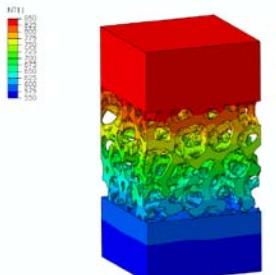


65ppi,15%

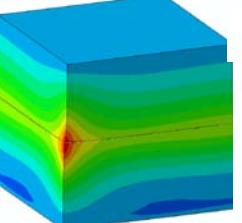
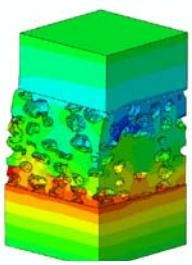
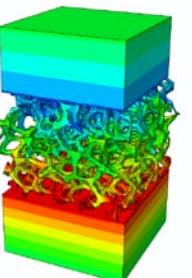
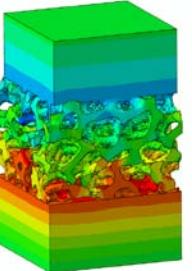


Modeling of Nb Foam

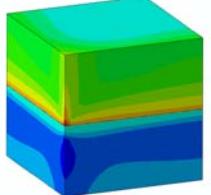
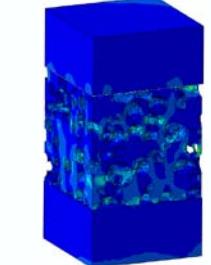
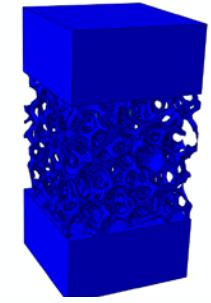
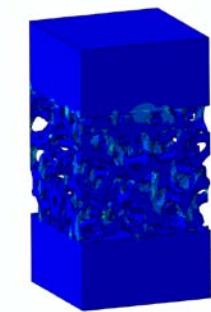
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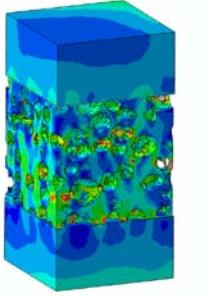
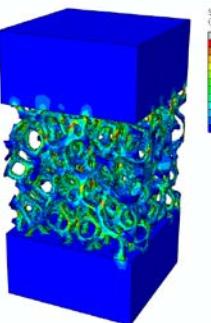
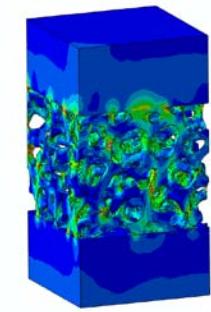
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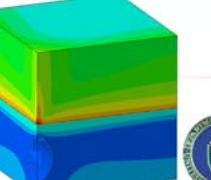
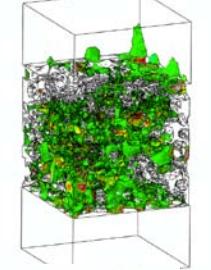
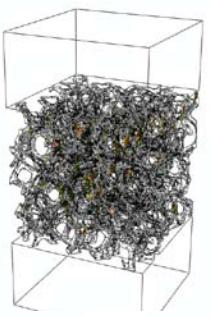
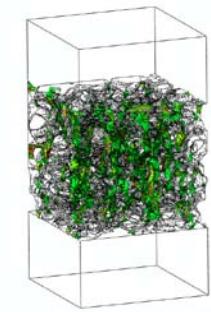
Mises All



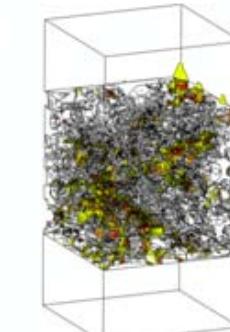
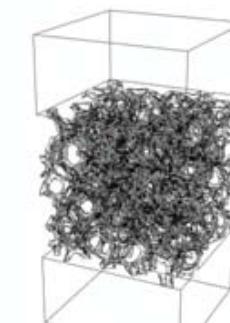
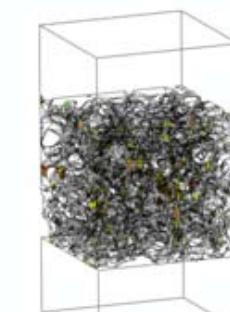
Maximum



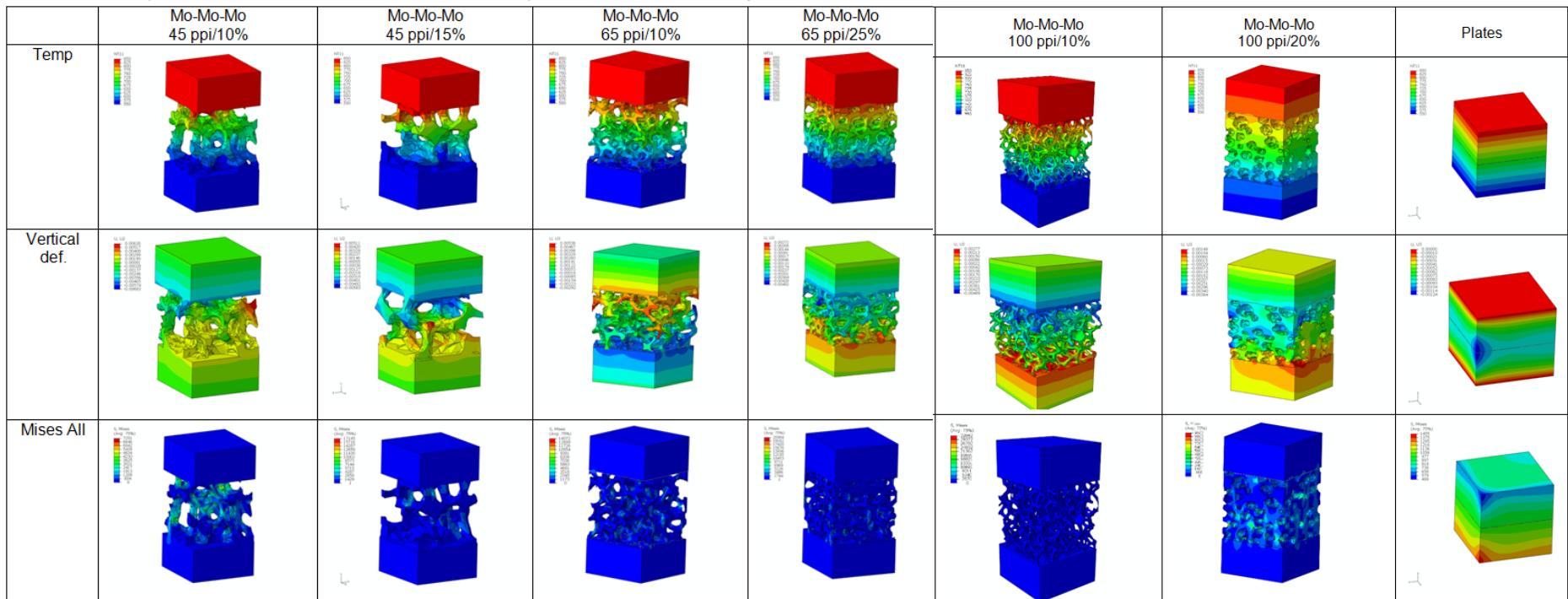
Over 500



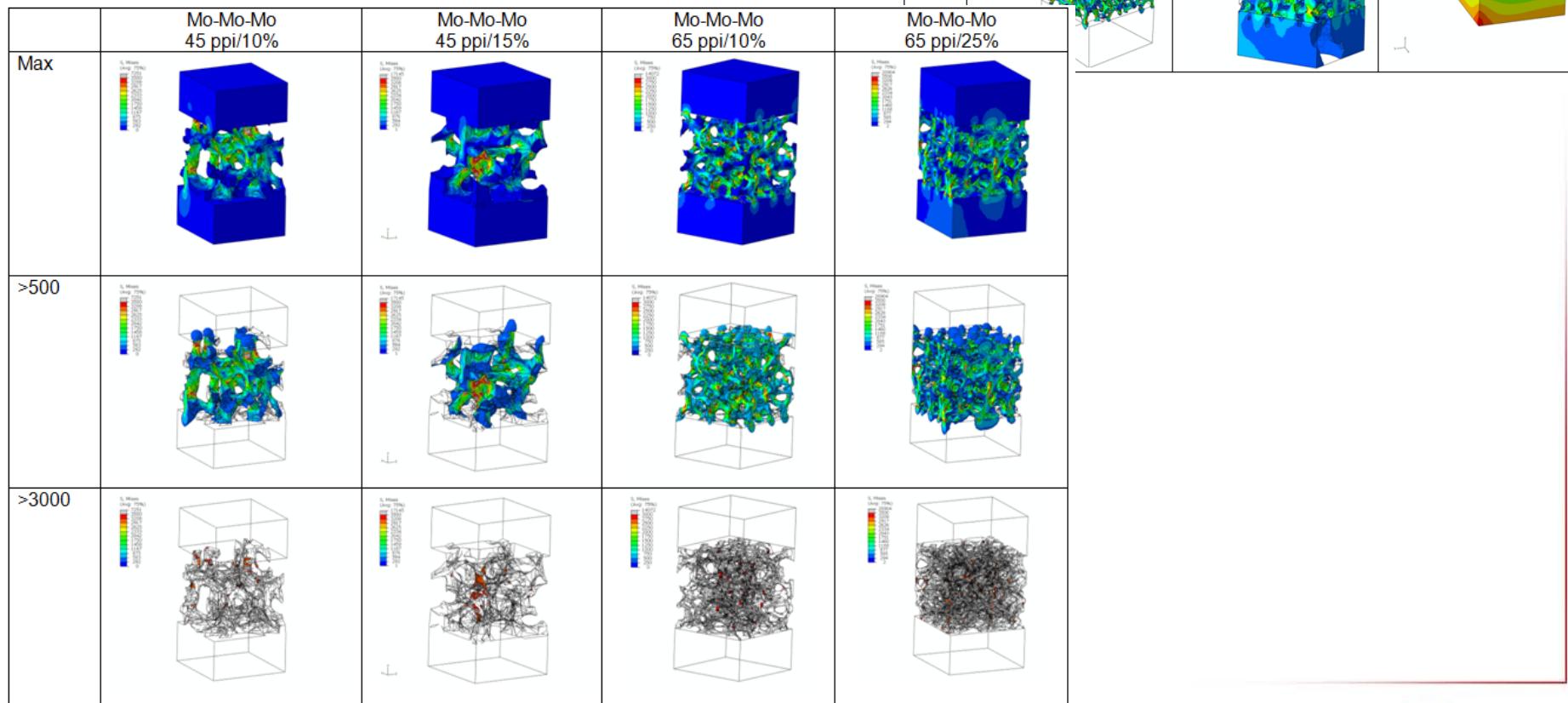
Over 700



Modeling of Mo Foam



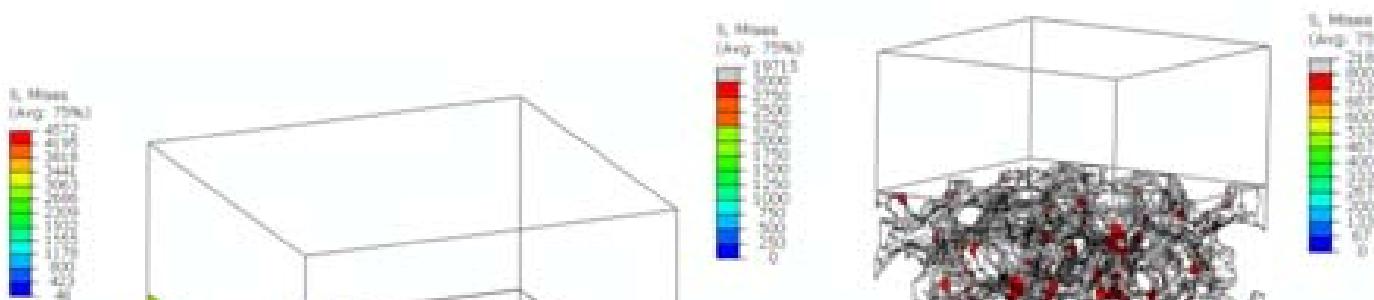
Modeling of Mo Foam



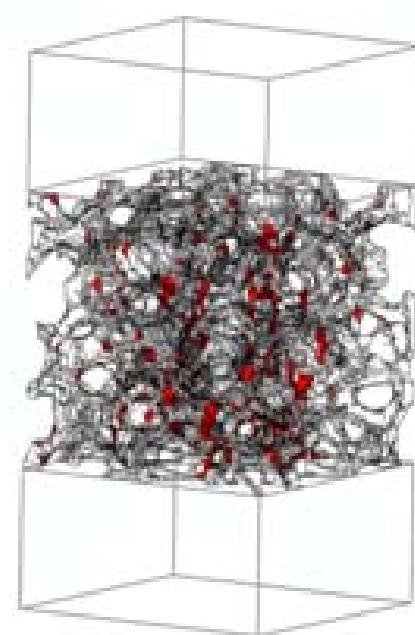
Thermal stress summary

- Nb foam with 45ppi 10% dense has the lowest thermal stress of all, followed by Mo and SiC (roughly x3 and x4 higher)
- The SiC foam with 65 ppi 10% density has the lowest stress for the SiC foams. The 100 ppi cases were higher.
- Stresses increased with density. Effect of ppi not as clear.
- In all cases the foam reduces the stress in the faceplates as expected, the Nb foam by an order of magnitude.
- The SiC foam was not as effective because of higher stresses in the ligaments, but stresses in the faceplates were still very low.

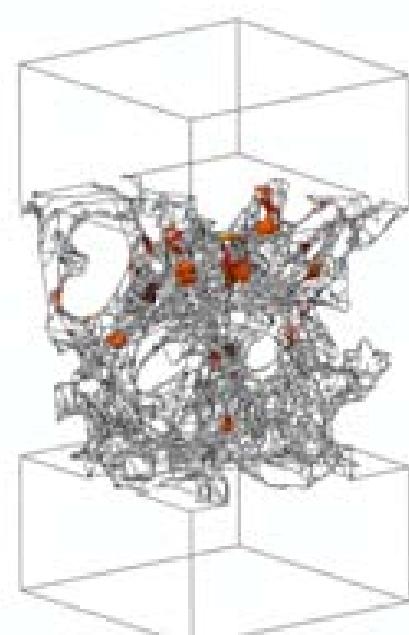
Plates (over 3000)



65ppi, 10% SiC foam
(over 3000)



45ppi, 10% Nb foam
(over 700)





Concluding remarks

- modeling of porous media on micro-scale now possible
- 64-bit, 4 to 16-node MPI computations, 98 GB ram
- tomography useful for reverse engineering
- improvements in file translation and meshing, but still challenging
- Investigated effectiveness of foams to improve heat transfer
- CFD and thermal stress analysis of porous media
- refractory high temperature foams for Brayton applications
- applications to various gas/gas heat exchangers, recuperators, regenerators, LM/gas heat exchangers
- modeling of foams for thermal stress reduction and insulation